Hi-Rel Mixed Module Part Matrix

W X XXX X XXX X V - XXX XXX X X

White Electronic Designs Corp. — 1 position

Product Type — 2 positions
- SE = SRAM/EEPROM Mixed Multi-Chip Package
- SF = SRAM/Flash Mixed Multi-Chip Package

Number of Words — 3 (2, 1) positions

Word Factor — 1 position
- K = Kilo
- M = Mega

Bits per Word — 3 (2, 1) positions

Improvement Mark — 1 position
- N = No Connect for HIP only

Voltage — 1 position
- Blank = 5V power supply
- V = 3.3V power supply

Access Times (ns) — 3 (2, 1) positions

Package Type/Pin Configuration — 3 (2, 1) positions
- C = 32 DIP
- G2 = 68 CQFP (0.88" sq., 0.200" high)
- G2T = 68 CQFP (0.88" sq., 0.180" high)
- G2U = 68 CQFP (0.88" sq., 0.140" high)
- G1U = 68 CQFP (0.94" sq., 0.140" high)
- G1T = 68 CQFP (0.94" sq., 0.160" high)
- H = 66 PGA (HIP), (1.185" sq.)
- H1 = 66 PGA (HIP), (1.075" sq.)
- H2 = 66 PGA (HIP), (1.385" sq.)

Device Grade — 1 position
- Q = MIL-PRF-38534 Compliant
- M = Military Screened -55°C to +125°C
- I = Industrial -40°C to +85°C
- C = Commercial 0°C to +70°C

Lead Finish — 1 position
- Blank = Gold plated leads
- A = Solder Dip leads

Note:

Not all packages, speeds and other options are available on every product.
Please refer to the individual data sheet for option selection.

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